

### **Amendments to the Specification**

Please replace insertion 1A on page 1, line 2, with the following:

This application is a Divisional of application Serial no. 09/628,833, filed 07/31/00, now Patent 6,388,199, issued May 14, 2002.

### **Amendments to Claims**

Please amend claim 19 and add new claim 30. A complete listing of claims all and status indicators is set forth below. This listing of claims will replace all prior versions and listings of claims in the application.

1-18 (canceled).

19. (currently amended) A method of manufacturing an integrated circuit package comprising the acts of:

- (a) providing a substrate having a first surface and a second surface, the second surface configured to receive a plurality of solder balls thereon;
- (b) disposing a solder resist onto the second surface of the substrate;
- (c) selectively raising a ~~the~~ surface tension of the solder resist to create a first portion of the solder resist having a first surface tension and a second portion of the solder resist having a second surface tension higher than the first surface tension;
- (d) disposing a molding compound on the second portion of the solder resist; and